## SY87725L

### 2.5Gbps GPON/BPON ONU SERDES

## General Description

The SY87725L is a single chip transceiver for data rates up to 2.5 Gbps . On the receive side, it includes a complete clock recovery and data retiming circuit with an integrated 4-bit serial-to-parallel data converter. On the transmit side, it includes a synthesizer with an integrated 4-bit parallel-to-serial data converter.
The SY87725L receiver has a synthesizer that generates an internal clock from an externally supplied TTL or PECL REFCLK that can be either 155.52 MHz or 77.76 MHz . This internal clock can be used by the clock recovery PLL if an absence of transitions on the input serial data stream prevents normal clock recovery. This enables it to provide a stable clock source in the absence of transitions on the incoming serial data stream.
The transmit synthesizer uses the CLKIN parallel data clock to generate its own serial rate clock locked to CLKIN. This enables the transmit and receive to operate at different data rates.
The serial interface for both the transmit and receive functions feature industry standard high-speed differential CML I/O. The parallel interfaces feature highspeed LVDS I/O with an internal $100 \Omega$ termination on the LVDS inputs.
The first bit for the serial-to-parallel conversion can be moved using the RCV_SYNC input. The RCV_SYNC input enables the parallel word boundary to move up in time by one bit time for each pulse. This allows it to in effect "swallow" one bit each time the RCV_SYNC pulse is asserted.
Datasheets and support documentation can be found on Micrel's web site at: www.micrel.com.

## Features

- Single 3.3 V supply and 1 W typ. power consumption
- $2.5 \mathrm{G} / 1.25 \mathrm{G} / 625 \mathrm{Mbps}$ down stream
- $1.25 \mathrm{G} / 625 \mathrm{M} / 156 \mathrm{Mbps}$ up stream
- 4-bit Serdes with LVDS interfaces
- Serial Data input sensitivity of 30 mV typical
- Training mode for fast lock acquisition
- Link Fault Indicator (LFIN: "HIGH" = Locked)
- Separate training and MUX synthesizers
- Loop back function for diagnostics
- TTL-CML Translator for MAC-to-Laser diode driver burst control
- Selectable double data rate option for low cost FPGA/ASIC MAC implementation
- Available in Pb -Free ( $10 \mathrm{~mm} \times 10 \mathrm{~mm}$ ) 64-pin EPAD-TQFP


## Applications

- BPON/GPON/GEPON/EPON


## Markets

- FTTH/FTTP


## Functional Block Diagram



## Pin Configuration



## 64-Pin EPAD-TQFP (T64-1)

## Ordering Information

| Part Number | Package <br> Type | Operating <br> Range | Package Marking | Lead <br> Finish |
| :--- | :---: | :---: | :---: | :---: |
| SY87725LHY | H64-1 | Industrial | SY87725LHY with <br> Pb-Free bar-line indicator | Pb-Free <br> Matte-Sn |
| SY87725LHYTR |  |  |  |  |

## Notes:

1. Contact factory for die availability. Dice are guaranteed at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, DC electricals only.
2. Tape and Reel

## Pin Description

receive section signals

| Pin Number | Pin Name | Pin Description |
| :---: | :---: | :---: |
| 55, 56 | SINP, SINN | Serial Data In (Differential LVPECL Input): This input receives the serial differential data stream. An internal PLL recovers the embedded clock and data. |
| 60, 61 | REFCLKP, REFCLKN, | Reference Clock (TTL or Differential LVPECL Input): This input accepts either singleended TTL or differential LVPECL signals and is used as the reference for the internal frequency synthesizer and the "training" frequency for the receiver PLL to keep it centered in the absence of data at the SIN input. The REFCLKN input has an internal reference circuit that applies the threshold voltage in case of a single-ended TTLsignal at REFCLKP. REFCLKN has an internal $75 \mathrm{k} \Omega$ to GND and can be left open in that case. |
| 15 | REFFREQSEL | Reference Clock Frequency Select (TTL Input): Selects REFCLK frequency of 77.76 MHz when LOW or 155.52 MHz when HIGH. |
| 6, 7 | RCV_PLLRP, RCV_PLLRN | Clock Recovery PLL Loop Filter: External loop filter pins for the receive PLL. |
| 1, 2 | RCV_PLLSN, RCV_PLLSP | Clock Synthesis PLL Loop Filter: External loop filter pins for the clock synthesis PLL. |
| 59 | RCV_SYNC | Receive Synchronizer (TTL Input): Single-ended asynchronous input to set the word boundary on the 4-bit parallel data |
| 3, 5 | RCV_FSELO, <br> RCV_FSEL1 | Receive Frequency Control (TTL Inputs): Two single-ended frequency selects for receive synthesizer. |
| $\begin{aligned} & 39,40, \\ & 41,42, \\ & 43,44, \\ & 45,46 \end{aligned}$ | DOUTOP, DOUTON, DOUT1P, DOUT1N, DOUT2P, DOUT2N, DOUT3P, DOUT3N | Parallel Data Out (LVDS Outputs): These are the four pairs of receive parallel data outputs. |
| 33, 34 | CLKOUT2P, CLKOUT2N | Parallel Clock Out (LVDS Output): This output is the recovered clock at the transmit byte clock rate and provides a clock that can be used as a reference clock to drive CLKIN. |
| 36, 37 | CLKOUTP, CLKOUTN | Parallel Clock Out (LVDS Output): This output is the recovered clock divided by 4 or 8 to provide the parallel data rate clock. |
| 18 | LFIN | Link Fault Indicator (TTL Output): When HIGH, LFIN indicates CDR is "in-lock" and when LOW it indicates CDR loss-of-lock. |
| 63 | RCV_DDRSEL | Double Data Rate Select (TTL Input): Selects either parallel data rate clock for normal operation or one-half of parallel data rate clock for double data rate applications. |
| 62 | CD | Carrier Detect Input (LVPECL input): When HIGH, CD indicates the carrier is present and when LOW it indicates the loss of carrier. |

## TRANSMIT SECTION SIGNALS

| $25,26,27$, <br> $28,29,30$, <br> 31,32 | DINOP, DINON, <br> DIN1P, DIN1N, <br> DIN2P, DIN2N, <br> DIN3P, DIN3N | Parallel Data In (LVDS Inputs): These are the four pairs of transmit parallel data <br> inputs. Each Differential pair has a $100 \Omega$ internal termination across the pair. |
| :---: | :---: | :--- |
| 22,23 | CLKINP, CLKINN | Parallel Clock In (LVDS Input): This input is the transmit parallel (byte-rate) clock. |
| 10,14 | XMT_FSELO, <br> XMT_FSEL1 | Transmit Frequency Control (TTL Inputs): Two single-ended frequency selects for <br> transmit synthesizer. |
| 11,12 | XMT_PLLSN, <br> XMT_PLLSP | Clock Synthesis PLL Loop Filter: External loop filter pins for the clock synthesis PLL. |
| 49,50 | SOUTP, SOUTN | Serial Data Out (Differential CML Output): This is the serial differential data stream <br> output. |
| 24 | XMT_DDRSEL | Double Data Rate Select (TTL Input): Selects either parallel data rate clock for normal <br> operation or one-half of parallel data rate clock for double data rate applications. |

## LOOPBACK CONTROLS

| Pin Number | Pin Name | Pin Description |
| :---: | :--- | :--- |
| 16,17 | XMT_CNTRLO, <br> XMT_CNTRL1 | Transmit Loop back Multiplexer Control (TTL Inputs): Two single-ended control lines <br> to control the data flow for remote loop back or normal serial data output. |
| 4,64 | RCV_CNTRLO, <br> RCV_CNTRL1 | Receive Loop back Multiplexer Control (TTL Inputs): Two single-ended control lines <br> to control the data flow for local loop back or recovered serial data into the 1:4 <br> DeMUX. |

TRANSLATOR SIGNALS

| 48 | IN | Signal from MAC to be translated (TTL Input) |
| :---: | :---: | :--- |
| 52,53 | OUTP, OUTN | Signal to Laser Diode Driver (CML Differential Output) |

POWER PINS AND TEST PIN

| 13 | Testb | Test Mode Pin: When held LOW activates test mode. (For factory use only, leave <br> open for normal operation.) |
| :---: | :--- | :--- |
| 20 | Test | Test Mode Pin: When held HIGH activates test mode. (For factory use only, must be <br> tied to GND for normal operation.). |
| 8 | VCCA | Analog Power: Connect to +3.3V power supply. Bypass with $0.1 \mu \mathrm{~F} / / 0.1 \mu \mathrm{~F}$ low <br> ESR capacitors as close to VCCA pin as possible. |
| 9 | GNDA | Analog Ground pin and exposed pad must be connected to the same ground plane. |
| $19,38,47,54$, <br> 57 | VCC | Core Power: Connect to +3.3V power supply. Bypass with $0.1 \mu \mathrm{~F} / / 0.1 \mu \mathrm{~F}$ low <br> ESR capacitors as close to VCC pins as possible. |
| $21,35,58$ | GND, Exposed Pad | Core Ground: Ground pins and exposed pad must be connected to the same ground <br> plane. |
| 51 | VCCO | CML Output Power: Connect to +3.3V power supply. Bypass with <br> $0.1 \mu \mathrm{~F} / / 0.1 \mu \mathrm{~F}$ low ESR capacitors as close to VCCO pin as possible. |

## Functional Description

The SY87725L is a fully integrated transceiver with an integrated serial-to-4-bit DeMUX and 4-bit-to-serial Multiplexer.

## Receive Section

## Clock and Data Recovery Function

The Clock Recovery function includes a synthesizer that generates a stable frequency based on the REFCLK input. The REFCLK input can be either a differential PECL input or a single-ended TTL input. It can also be either 77.76 MHz or 155.52 MHz as selected by REFFREQSEL. The synthesized frequency derived from the REFCLK is within 1000ppm of the incoming serial data rate and is used by the Clock and Data Recovery (CDR) circuit to "train" to the correct frequency range. This training function minimizes the acquisition time for the CDR to lock onto the incoming data stream by keeping the CDR frequency within close range of the recovered clock in the case of loss of data.

The RCV_FSEL0 and RCV_FSEL1 inputs select the receive data rate. For example, these inputs can be used to select an OC-48, OC-24 or OC-12 data rate for the serial data in, SIN. The typical input sensitivity of SIN is 30 mV .
The Clock Recovery function also generates CLKOUT2 that is controlled by the XMT_DDRSEL input for regular or double data rate applications. If a clean, low-jitter byte-rate clock is not available for CLKIN to the Transmit Synthesizer, CLKOUT2 can be used as the reference clock.

## DeMUX Function

The recovered serial data from the CDR is converted to a 4-bit parallel word by a 1:4 de-multiplexer. The serial-to-parallel conversion sequence is LSB first, i.e. first serial bit in is DOUT0, second serial bit in is DOUT1, etc. A RCV_SYNC pulse input is used to set the word boundary of the 4-bit parallel word. A single pulse, applied asynchronously for a minimum of two input clock cycles to the RCV_SYNC input, causes the start bit of conversion to occur one bit earlier.

The CLKOUT output is the parallel data rate clock to be used with the DOUT parallel data from the DeMUX. It is selectable by the RCV_DDRSEL input to be either at the parallel data rate or one-half the parallel data rate for double data rate applications.

## Transmit Section

## Synthesizer Function

The SY87725L Transmit Synthesizer uses the divide-by4 parallel clock input or a divide-by-8 clock input when double data rate is selected as a reference clock. The XMT_FSELO and XMT_FSEL1 inputs select the TX data rate. For example, these inputs can be used to select an OC-24, OC-12 or OC-3 rate for the serial data out, SOUT.

## MUX Function

The 4-bit parallel data input is converted to a serial data stream with a $4: 1$ multiplexer. The parallel-to-serial conversion sequence is LSB first, i.e. DINO will be shifted out first, followed by DIN1, etc.

## Auto-Alignment Function

Because the 4-bit parallel data input can have an arbitrary phase relationship with the transmit byte-rate clock input (CLKIN), an auto-alignment function is included in the transmit parallel-to-serial circuit.
The phase of the 4-bit parallel data is sampled and compared with the phase of the incoming CLKIN. If the clock and data are not in the proper phase relationship, the phase is internally adjusted to insure that the data will be sampled at the optimal time. This can result in a variation of the latency between the parallel data in and the serial data out (TDOUT) of up to three CLKIN clock cycles.

## Loopback Function

Two $3: 1$ multiplexers are provided to allow Local or Remote Loopback.

## Frequency Selections

| XMT_FSEL0 | XMT_FSEL1 | TX DATA RATE |
| :---: | :---: | :---: |
| 0 | 0 | 155.52 Mbps |
| 1 | 0 | 622.08 Mbps |
| 0 | 1 | 1244.16 Mbps |
| 1 | 1 | N/A |

Table 1. Transmit Frequency Selection

| RCV_FSELO | RCV_FSEL1 | RX DATA RATE |
| :---: | :---: | :---: |
| 0 | 0 | N/A |
| 1 | 0 | 622.08 Mbps |
| 0 | 1 | 1244.16 Mbps |
| 1 | 1 | 2488.32 Mbps |

Table 2. Receive Frequency Selection

| XMT_FSELO | XMT_FSEL1 | XMT_DDRSEL | CLKOUT2 |
| :---: | :---: | :---: | :---: |
| 0 | 0 | 0 | 38.88 MHz |
| 1 | 0 | 0 | 155.52 MHz |
| 0 | 1 | 0 | 311.04 MHz |
| 1 | 1 | 0 | N/A |
| 0 | 0 | 1 | 19.44 MHz |
| 1 | 0 | 1 | 77.76 MHz |
| 0 | 1 | 1 | 155.52 MHz |
| 1 | 1 | 1 | N/A |

Table 3. CLKOUT2 Frequency Selection

| RCV_CNTRL0 | RCV_CNTRL1 | XMT_DDRSEL | RCV_DDRSEL | DOUT | CLKOUT |
| :---: | :---: | :---: | :---: | :---: | :---: |
| 0 | 0 | 0 | 0 | N/A | N/A |
| 1 | 0 | 0 | 0 | DIN | CLKIN |
| 0 | 1 | 0 | 0 | SIN (bypass) | REFCLK/4 |
| 1 | 1 | 0 | 0 | SIN (Recovered Data) | Recovered Clock/4 |
| 0 | 0 | 1 | 0 | N/A | N/A |
| 1 | 0 | 1 | 0 | DIN | 2 * CLKIN |
| 0 | 1 | 1 | 0 | SIN (bypass) | REFCLK/4 |
| 1 | 1 | 0 | 0 | SIN (Recovered Data) | Recovered Clock/4 |
| 0 | 0 | 0 | 1 | N/A | N/A |
| 1 | 1 | 0 | 1 | DIN | CLKIN/2 |
| 0 | 0 | 1 | 1 | 1 | SIN (bypass) |
| 1 | 0 | 1 | 1 | 1 | NEFCLK/8 |
| 1 | 1 | 1 | 1 | DIN | Recovered Clock/8 |
| 0 | 1 | 0 | SIN (bypass) | N/A |  |
| 1 | 1 | 1 | RIN (Recovered Data) | Recovered Clock/8 |  |

Table 4. Local Loopback Controls

| XMT_CNTRL0 | XMT_CNTRL1 | SOUT |
| :---: | :---: | :---: |
| 0 | 0 | SIN (Bypass CDR) |
| 1 | 0 | Recovered Clock (from SIN) |
| 0 | 1 | Recovered Data (from SIN) |
| 1 | 1 | DIN (Normal Data Flow) |

Table 5. Remote Loopback Controls

## Loop Filter Components



|  | $\mathbf{R}$ | $\mathbf{C}$ |
| :---: | :---: | :---: |
| Rcv_PLLS | $1.2 \mathrm{k} \Omega$ | $1 \mu \mathrm{~F}$ |
| Rcv_PLLR | $390 \Omega$ | $1 \mu \mathrm{~F}$ |
| XMT_PLLS | $1.2 \mathrm{k} \Omega$ | $1 \mu \mathrm{~F}$ |

Table 6. Synthesizer \& Clock Recovery Loop Filter Values

| Absolute Maximum Ratings ${ }^{(1)}$ |
| :---: |
| Supply Voltage ( $\mathrm{V}_{\mathrm{cc}}$ ) ............................ -0.5 V to +4.6 V |
| Input Voltage ( $\mathrm{V}_{\mathbb{N}}$ ) .................................... -0.5 V to $\mathrm{V}_{\text {C }}$ |
| LVDS Output Current (lout)................................. $\pm 10 \mathrm{~mA}$ |
|  |  |
|  |
| Current........................................................ $\pm 25 \mathrm{~mA}$ |
| Lead Temperature (soldering, 20 sec.) ................ $+260^{\circ} \mathrm{C}$ |
|  |

## Operating Ratings ${ }^{(2)}$

Supply Voltage ( $\mathrm{V}_{\mathrm{cc}}$ ) ........................... +3.15 V to +3.45 V
Ambient Temperature ( $\mathrm{T}_{\mathrm{A}}$ ) ..................... $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$
Package Thermal Resistance ${ }^{(3)}$
MLF ${ }^{\circledR} \theta_{\text {נв }}$
Still-Air ........................................................ $35^{\circ} \mathrm{C} / \mathrm{W}$
MLF ${ }^{\circledR} \psi_{\text {s }}$
Junction-to-Board .......................................... $7^{\circ} \mathrm{C} / \mathrm{W}$

## DC Electrical Characteristics ${ }^{(4)}$

$\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless noted.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $V_{\mathrm{cc}}$ | Power Supply |  | 3.15 | 3.3 | 3.45 | V |
| $\mathrm{I}_{\mathrm{Cc}}$ | Power Supply Current | No load, max. $\mathrm{V}_{\mathrm{cc}}$ |  | 300 | 380 | mA |

## LVPECL Electrical Characteristics ${ }^{(4)}$

$\mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{V}_{\mathrm{CCO}}=3.3 \mathrm{~V} \pm 5 \% ; \mathrm{GND}=\mathrm{GNDA}=0 \mathrm{~V} ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{IH}}$ | Input HIGH Voltage |  | $\mathrm{V}_{\mathrm{cc}}-1.165$ |  | $\mathrm{~V}_{\mathrm{cc}}-0.88$ | V |
| $\mathrm{~V}_{\mathrm{IL}}$ | Input LOW Voltage |  | $\mathrm{V}_{\mathrm{cc}}-1.810$ |  | $\mathrm{~V}_{\mathrm{cc}}-1.475$ | V |

## CML Output Electrical Characteristics ${ }^{(4)}$

$\mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{V}_{\mathrm{CCO}}=3.3 \mathrm{~V} \pm 5 \% ; \mathrm{GND}=\mathrm{GNDA}=0 \mathrm{~V} ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $V_{\text {OH }}$ | Output HIGH Voltage |  | $\mathrm{V}_{\mathrm{CC}}-0.020$ | $\mathrm{~V}_{\mathrm{CC}}-0.010$ | $\mathrm{~V}_{\mathrm{CC}}$ | V |
| V OUT | Output LOW Voltage |  | 325 | 400 |  | mV |
| V $_{\text {DIFF_OUT }}$ | Differential Output Voltage |  | 650 | 800 |  | mV |

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package Thermal Resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB. $\theta_{\mathrm{JB}}$ assumes a 4-layer PCB. $\psi_{\mathrm{JA}}$ in still air unless otherwise stated.
4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established

## LVTTL/CMOS DC Electrical Characteristics ${ }^{(5)}$

$\mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{V}_{\mathrm{CCO}}=3.3 \mathrm{~V} \pm 5 \% ; \mathrm{GND}=\mathrm{GNDA}=0 \mathrm{~V} ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{IH}}$ | Input HIGH Voltage |  | 2.0 |  | $\mathrm{~V}_{\mathrm{CC}}$ | V |
| $\mathrm{V}_{\mathrm{IL}}$ | Input LOW Voltage |  | 0 |  | 0.8 | V |
| $\mathrm{I}_{\mathrm{IH}}$ | Input HIGH Current |  | -125 |  | 30 | $\mu \mathrm{~A}$ |
| $\mathrm{I}_{\mathrm{IL}}$ | Input LOW Current |  | -300 |  |  | $\mu \mathrm{~A}$ |
| $\mathrm{~V}_{\mathrm{OH}}$ | Output HIGH Voltage | $\mathrm{I}_{\mathrm{OH}}=100 \mu \mathrm{~A}$ | 2.0 |  |  | V |
| $\mathrm{~V}_{\mathrm{OL}}$ | Output LOW Voltage | $\mathrm{I}_{\mathrm{OI}}=4 \mathrm{~mA}$ |  |  | 0.5 | V |
| $\mathrm{I}_{\mathrm{OS}}$ | Output Short-Circuit Current | V OUT $=0 \mathrm{~V}$ (max. 1sec.) | -100 |  | -15 | mA |

## LVDS DC Electrical Characteristics ${ }^{(5)}$

$\mathrm{V}_{C C}=\mathrm{V}_{C C A}=\mathrm{V}_{\mathrm{CCO}}=3.3 \mathrm{~V} \pm 5 \% ; G N D=G N D A=0 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=100 \Omega$ across output pair; $\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted.

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :---: | :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IN-Range }}$ | Input Voltage Range |  | 0 |  | 2.4 | V |
| $\mathrm{~V}_{\text {IN }}$ | Input Voltage Swing |  | 100 |  | 500 | mV |
| $\mathrm{V}_{\text {IIFF-IN }}$ | Differential Input Voltage Swing |  | 200 |  | 1000 | mV |
| $\mathrm{R}_{\text {IN }}$ | Input Differential <br> Resistance |  | 85 | 100 | 115 | $\Omega$ |
| $\mathrm{~V}_{\text {OUT }}$ | Output Voltage Swing |  |  | 325 |  | mV |
| $\mathrm{V}_{\text {DIFF-OUT }}$ | Differential Output Voltage <br> Swing |  | 1.125 |  | 1.275 | V |
| $\mathrm{~V}_{\text {OCM }}$ | Output Common Mode <br> Voltage |  | -50 |  | +50 | mV |
| $\Delta \mathrm{V}_{\text {OCM }}$ | Change in Output Common <br> Mode Voltage |  |  |  |  | mV |

Note:
5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

## AC Electrical Characteristics ${ }^{(6)}$

$\mathrm{V}_{\mathrm{CC}}=\mathrm{V}_{\mathrm{CCA}}=\mathrm{V}_{\mathrm{CCO}}=3.3 \mathrm{~V} \pm 5 \% ; \mathrm{GND}=\mathrm{GNDA}=0 \mathrm{~V} ; \mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$, unless otherwise noted

| Symbol | Parameter | Condition | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SIN MAX | SIN Maximum Data Rate |  | 2.5 |  |  | Gbps |
| SOUT $_{\text {MAX }}$ | SOUT Maximum Data Rate |  | 1.25 |  |  | Gbps |
| $t_{\text {ACQ }}$ | Acquisition Lock Time |  |  |  | 15 | $\mu \mathrm{s}$ |
|  | Frequency Difference, LFIN shows Out-of-Lock |  |  | 1000 |  | ppm |
| $\mathrm{t}_{\text {CPWH }}$ | REFCLK Pulse Width HIGH Time |  | 2.5 |  |  | ns |
| tcpwL | REFCLK Pulse Width LOW Time |  | 2.5 |  |  | ns |
| tskew | Parallel CLKOUT to Parallel Data Out Skew | See "Figure 1" | -150 |  | +150 | ps |
| $\mathrm{t}_{\mathrm{PR}}, \mathrm{t}_{\text {PF }}$ | CML Output Rise/Fall Time (20\% to 80\%) | At full output swing | 40 | 70 | 100 | ps |
| $t_{\text {LR }}, \mathrm{t}_{\text {LF }}$ | LVDS Output Rise/Fall Time (20\% to 80\%) | At full output swing | 100 | 250 | 400 | ps |
| $\mathrm{t}_{\mathrm{DC}}$ | CLKOUT, CLKOUT2 Duty Cycle |  | 45 |  | 55 | \% |

Note:
6. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

## Timing Diagrams

## Receive Timing



Figure 1. 1:4 Serial-to-Parallel Conversion


Figure 2. 1:4 Serial-to-Parallel Conversion with SYNC Pulse

## Transmit Timing



Figure 3. 4:1 Parallel-to-Serial Conversion

## Applications Sections

This section illustrates the various operating modes of the SY87725L with the appropriate control signals.

## Normal Data Flow

## Receive Section

The diagram below shows the data paths in a normal operating mode. In this case, downstream data at a serial rate of 2.5 Gbps is arriving at SIN and the recovered 4-bit parallel data is exiting at DOUT at 625 Mbps . This is not the double data rate mode (DDR) so the parallel rate is the serial rate $\div 4$.

## Transmit Section

On the transmit side, the upstream data appears at DIN in a 4-bit wide parallel format at 312.5 Mbps and exits at SOUT at a 1.25 Gbps serial rate. The CLKIN input is synchronous with the parallel data at DIN.
The loopback control signals RCV_CNTRLO, RCV_CNTRL1, XMT_CNTRL0, XMT_CNTRL1 shown in the table below select the clock and data paths for normal operation. The RCV_DDRSel input is selecting the CLKOUT to be in normal rate ( $\div 4$ ) mode.


Figure 4. Normal Data Flow

| RCV_CNTRL0 | RCV_CNTRL1 | XMT_CNTRL0 | XMT_CNTRL1 | RCV_DDRSEL |
| :---: | :---: | :---: | :---: | :---: |
| 1 | 1 | 1 | 1 | 0 |

Table 7. Loopback and DDR Select Control Signals

| RCV_FSEL0 | RCV_FSEL1 | XMT_FSEL0 | XMT_FSEL1 |
| :---: | :---: | :---: | :---: |
| 1 | 1 | 0 | 1 |

Table 8. Transmit and Receive Frequency Select

## Normal Data Flow (Secondary Clock)

## Receive Section

This mode is identical to the Normal Mode in the
previous section, but utilizes CLKOUT2 to be used as the transmit parallel clock. In this mode, CLKOUT2 must be externally connected to CLKIN as shown in the block diagram below.


Figure 5. Normal Data Flow

| RCV_CNTRL0 | RCV_CNTRL1 | XMT_CNTRLO | XMT_CNTRL1 | RCV_DDRSEL |
| :---: | :---: | :---: | :---: | :---: |
| 1 | 1 | 1 | 1 | 0 |

Table 9. Loopback and DDR Select Control Signals

| RCV_FSEL0 | RCV_FSEL1 | XMT_FSEL0 | XMT_FSEL1 |
| :---: | :---: | :---: | :---: |
| 1 | 1 | 0 | 1 |

Table 10. Transmit and Receive Frequency Select

## Remote Loopback Mode 00

This is the simplest of the loopback modes as its main purpose is to verify if the link is OK.

It is possible to combine this with Local Loopback modes; however, it is intended to be a stand-alone test mode.

REMOTE LOOPBACK DATA FLOW


Figure 6. Remote Loopback Data Flow

| XMT_CNTRL0 | XMT_CNTRL1 |
| :---: | :---: |
| 0 | 0 |

Table 11. Loopback Control Signals

## Remote Loopback Modes 01 and 10

These modes verify the operation of the CDR by
looping back the recovered clock or data.
The REFCLK is necessary for normal operation of the CDR.


Figure 7. Remote Loopback Recovered Clock Flow

| XMT_CNTRL0 | XMT_CNTRL1 |
| :---: | :---: |
| 1 | 0 |

Table 12. Loopback Control Signals


Figure 8. Remote Loopback Recovered Data Flow

| XMT_CNTRLO | XMT_CNTRL1 |
| :---: | :---: |
| 0 | 1 |

Table 13. Loopback Control Signals

## CDR Bypass Mode

This mode bypasses the CDR and feeds SIN directly into the DeMUX. Because the CDR is bypassed, there is no recovered clock in this mode. The RefClk is fed directly into the DeMUX and is the serial rate clock.

Therefore, in this mode only, the RefClk is not used by the Synthesizer but will be at the same frequency as the SIN data rate. In this mode the maximum SIN data rate is 155.52 Mbps and the matching RefClk frequency will be 155.52 MHz . The Data at SIN is sampled at the falling edge of REFCLK.

CDR BYPASS MODE DATA FLOW


Figure 9. CDR Bypass Mode

| RCV_CNTRL0 | RCV_CNTRL1 |
| :---: | :---: |
| 0 | 1 |

Table 14. Loopback Control Signals

## Local Loopback Mode

This mode loops the serial data out of the Mux back to the serial input of the DeMux. This allows the
operation of the Mux and DeMux to be verified through the parallel interface.

LOCAL LOOPBACK DATA FLOW


Figure 10. Local Loopback Data Flow

| RCV_CNTRL0 | RCV_CNTRL1 |
| :---: | :---: |
| 1 | 0 |

Table 15. Loopback Control Signals

## Package Information



## 64-Pin EPAD-TQFP (T64-1)

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